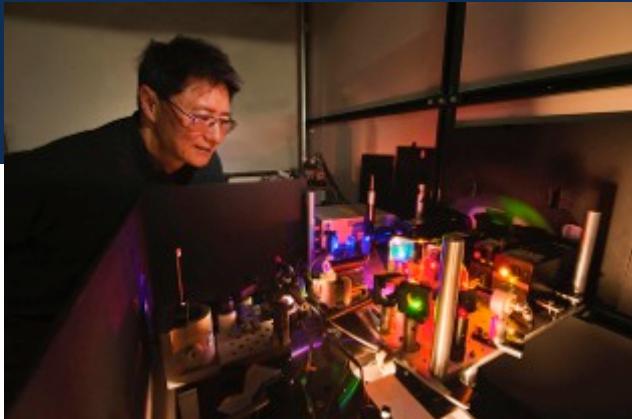


*Exceptional service in the national interest*



# Securing Trusted Rad-Hard Electronics for the Future

**Rich Dondero**

Microsystems Assessments I

[rdonder@sandia.gov](mailto:rdonder@sandia.gov)

Sandia National Laboratories

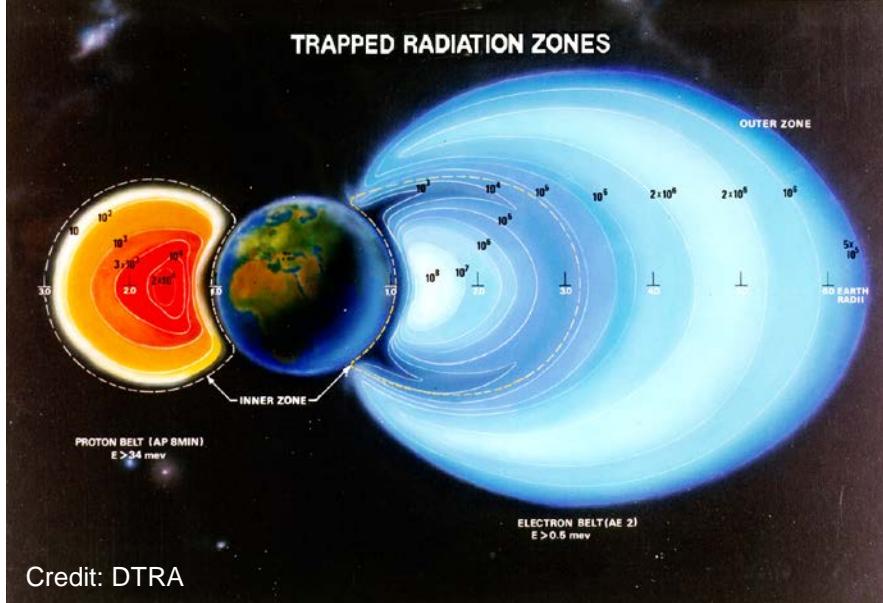
DMSMS 2015

December 3, 2015



Sandia National Laboratories is a multi-program laboratory managed and operated by Sandia Corporation, a wholly owned subsidiary of Lockheed Martin Corporation, for the U.S. Department of Energy's National Nuclear Security Administration under contract DE-AC04-94AL85000. SAND2015-365117

## Van Allen Rad Belts



Credit: DTRA



## Trusted Microelectronics

## Rad Hard Microelectronics



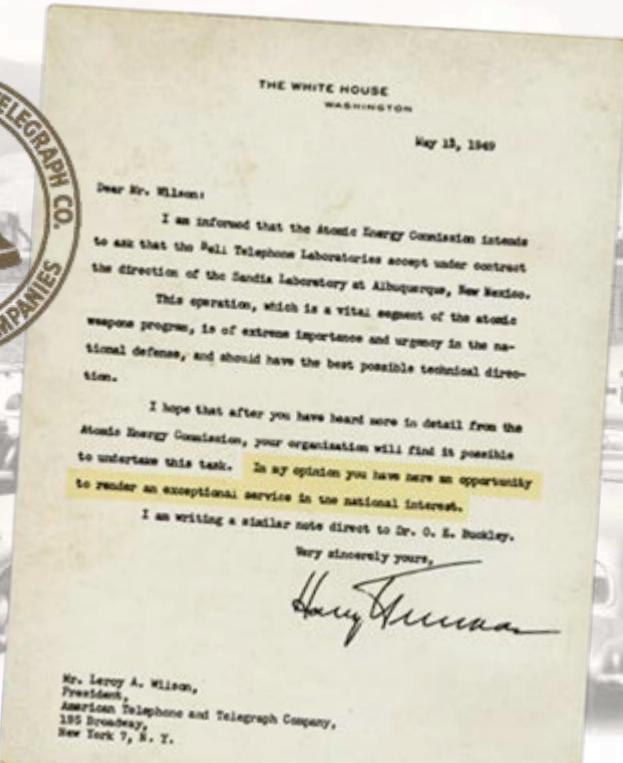
**Safe  
Secure  
Effective**



# Sandia's History

*Exceptional service in the national interest*

- July 1945: Los Alamos creates Z Division
- Nonnuclear component engineering
- November 1, 1949: Sandia Laboratory established



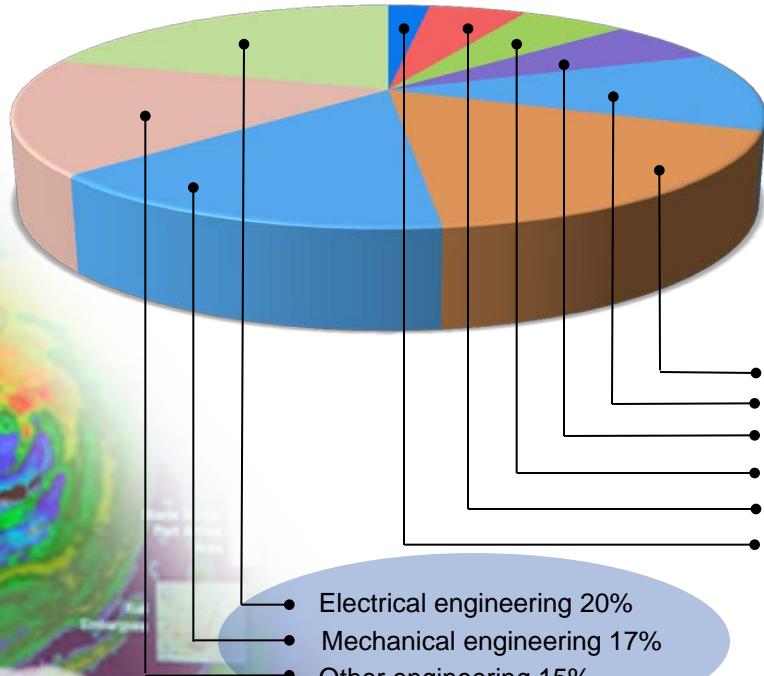
to undertake this task. In my opinion you have here an opportunity  
to render an exceptional service in the national interest.



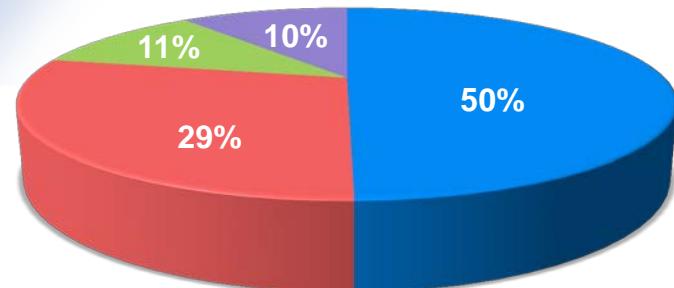
# Sandia National Laboratories

- Total Sandia workforce: 12,609
- Regular employees: 10,330
- Advanced degrees: 5,790 (56%)

## Technical staff (5,046) by discipline



**FY14 Operating Revenue  
\$2.7 billion**



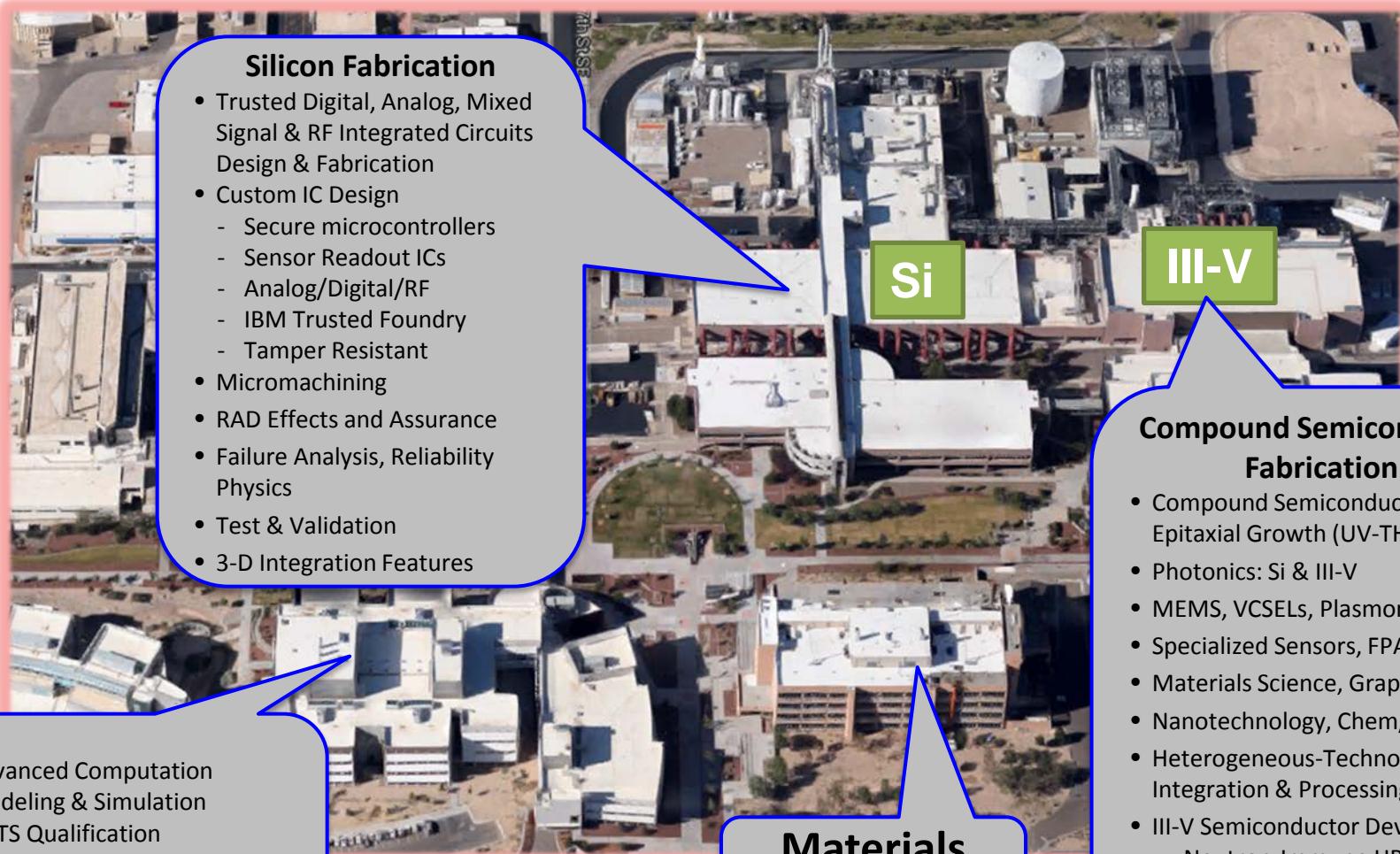
### (Operating Budget)

- Nuclear Weapons
- Defense Systems & Assessments
- Energy, Climate & Infrastructure Security
- International, Homeland, and Nuclear Security



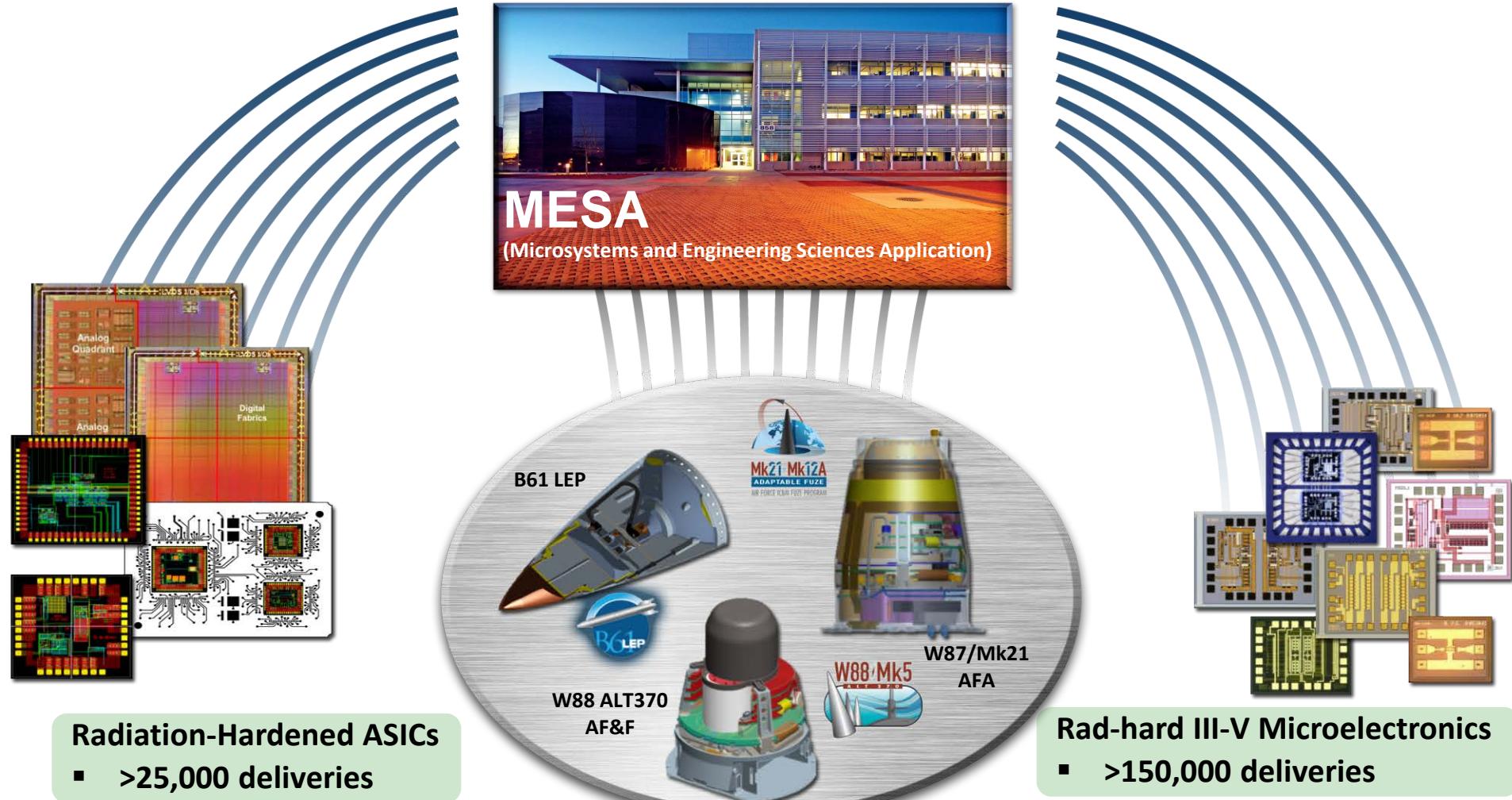
**Mostly in Albuquerque, NM**

# Microsystems and Engineering Sciences Applications (MESA): 400,000 Sq-ft Complex with >650 Employees



***MESA is a development and production facility for microsystem components and technology that cannot or should not be obtained commercially.***

# Manufactures Strategic Rad-Hard Trusted Components for Nuclear Weapons



***Trust environment (NW, DMEA)***

***Strong Failure Analysis, Reliability***

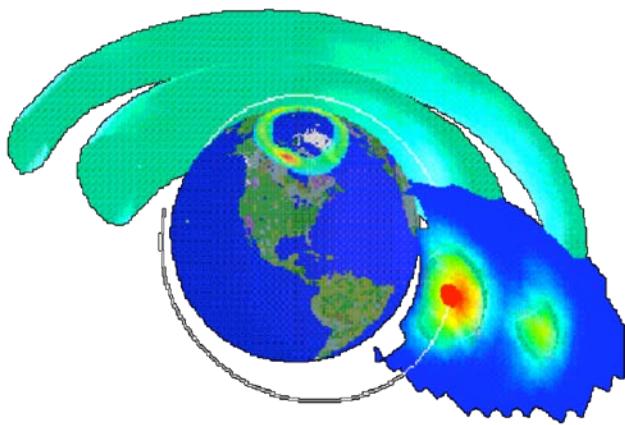
# Table of Contents

- Space Radiation Environments
- Nuclear Weapon Radiation Environments
- Microelectronics Rad-Hard Solutions
- Trust Issues
- Trust Solutions Today
- Trust Solutions Tomorrow
- Trusted & Strategic Rad-Hard Futures at Sandia
- An Ecosystem to Improve *Trustworthiness*

# Space Radiation Environments

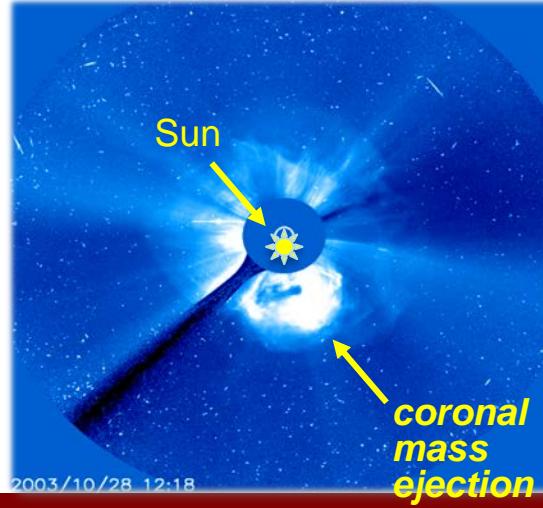
- The natural space radiation environment consists of trapped particle belts, solar events (flares and coronal mass ejections), and galactic cosmic rays
- Radiation can produce temporary malfunctions in electronics (e.g., single-event upset, single-event functional interrupts) or permanent degradation/failure (e.g., total ionizing dose, displacement damage, latchup/burnout)
- The impact of these effects can range from data corruption to instrument malfunction to mission failure

Trapped Particle Belts



J. Barth, 1997 NSREC

Solar Particle Events



SOHO (ESA & NASA)

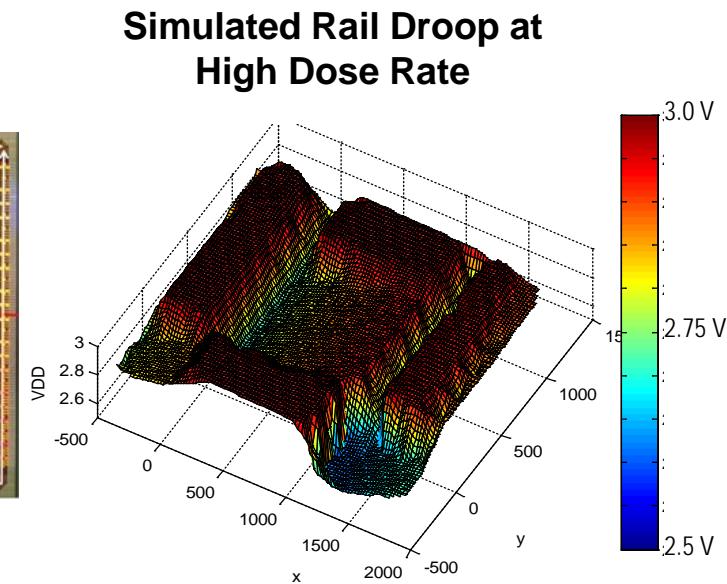
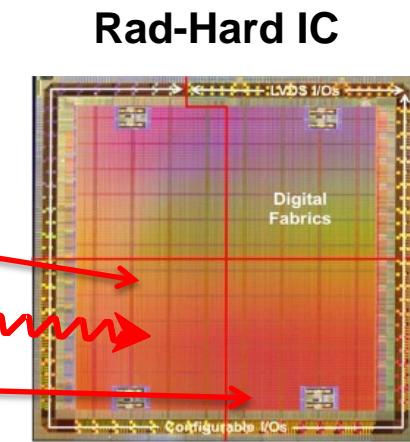
Galactic Cosmic Rays



Pierre Auger Observatory

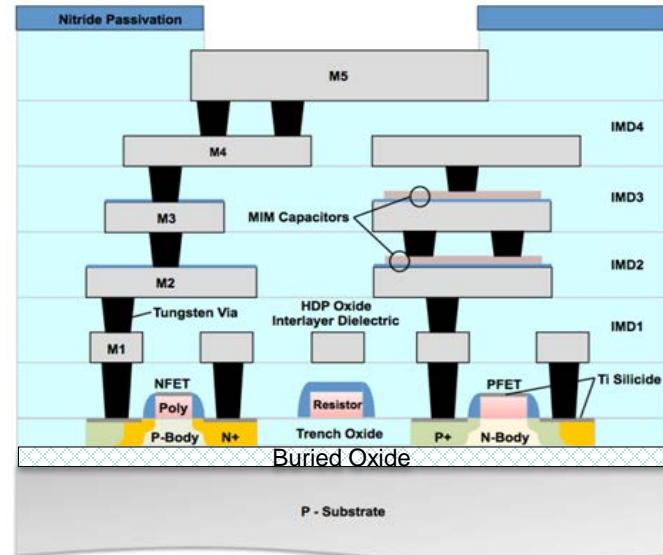
# Nuclear Weapon Radiation Environments

- The radiation environment near a detonated nuclear weapon contains large numbers of x-rays, gammas, and neutrons
- Some effects of this environment are similar to those of the natural space environment but different in scale (e.g., displacement damage effects in bipolar transistors), while others are unique to this extreme environment (e.g., dose-rate upset in integrated circuits)
- Detonation of nuclear weapons in space can also affect operation and longevity of critical space assets (commercial and military)



# Several Rad-Hard Solutions

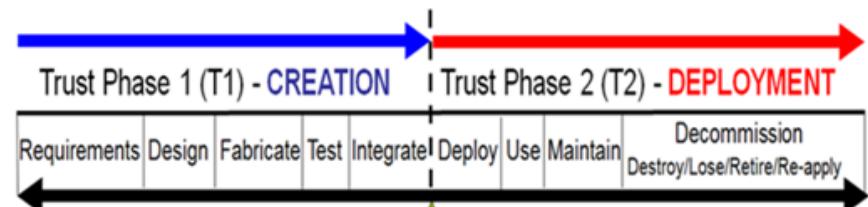
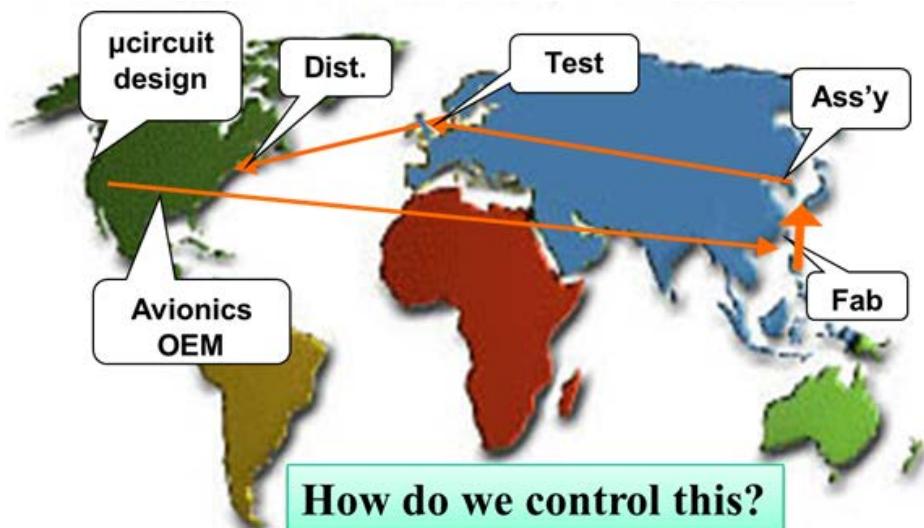
- Rad-Hard by Process (RHBP)
  - Honeywell: SOI CMOS at the 150-nm node, Rad-Hard products for satellite programs
  - Sandia National Labs
- Rad-Hard by Design (RHBD)
  - Championed by Boeing, USAF, DTRA, and others
  - Allows rad-hard at advanced CMOS nodes
- Upscreening of COTS
  - Aeroflex/Cobham
- The solutions depend on the requirements
  - “Strategic” rad-hard means different things to various customers
  - Strategic space vs. strategic nuclear weapons
- The rad-hardest solution is RHBP + RHBD
  - Generally this solution space is small
  - Honeywell, BAE Systems, Boeing Design Kit, Sandia National Laboratories, Northrop Grumman and more.



*Sandia's SOI CMOS7 Rad-Hard Technology*

# Trust: The Issues

- Counterfeit parts are big business - Legacy parts
- Cloning is becoming a serious threat – not easy to detect.
- The rise of malicious intent: denial of service, kill switches
- International supply chain – where is the chain of custody



Verification, Validation, Certification

Cradle to Grave Concerns

# Trust Solutions Today

- DMEA Accredited Trusted Foundry & TAPO
  - Global Foundries US 2
  - Formerly IBM TF: 52 Designs
- DMEA Trusted Suppliers - Many
  - Design to packaged parts to test
  - Roughly 60 accredited suppliers
- Legacy Parts: know your supply chain - Pedigree
- Counterfeit Detection – Verification/Validation
  - Several government and commercial services
  - Counterfeitors are adapting
  - Cloning detection – challenging

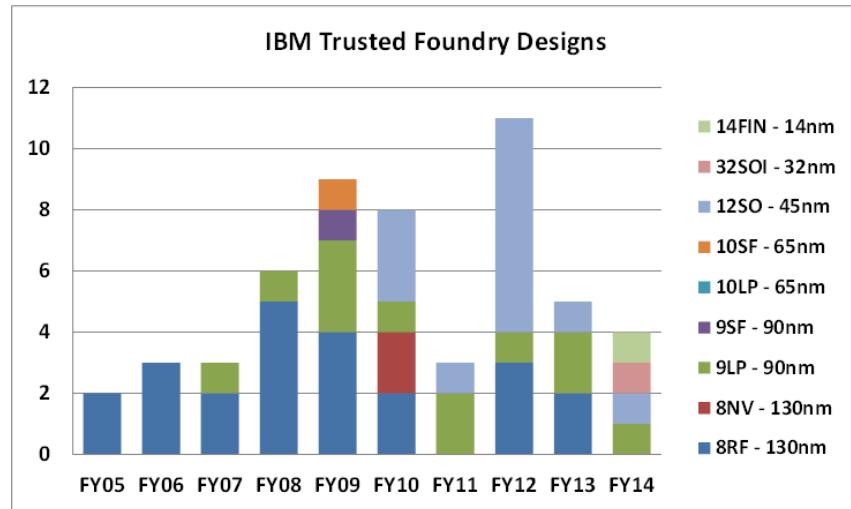


**NORTHROP GRUMMAN**

**LANSDALE**  
Semiconductor Inc.

**TOWERJAZZ**  
The Global Specialty Foundry Leader

**Honeywell** | Aerospace



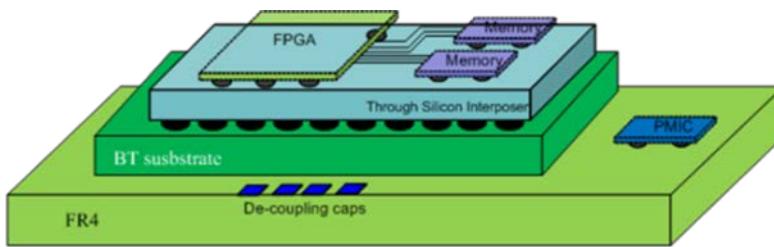
# Trust Solutions Tomorrow

- DMEA accredited, Trusted suppliers
  - Foundry consolidation increasing foreign ownership
  - Access to Trusted state-of-the-art microelectronics limited
- State-of-the-Art is not Trusted – R&D ideas to Mitigate
  - IARPA – TIC: Split BEOL/FEOL manufacturing flow
  - SHIELD: Provide a secure hardware root-of-trust which co-packaged with an electronic component
  - CRAFT: Significantly increase reuse of integrated circuit elements
  - DAHI: Diverse and Accessible Heterogeneous Integration: Manufacturing a device across multiple commercial locations while concealing its functionality
- Areas of Opportunity?
  - Trust Metrics: qualitative & quantitative
  - Trust Resiliency – Detect/Decide/Deter
  - Obfuscation techniques
  - Faster validation techniques
  - Model and Predict trustworthiness

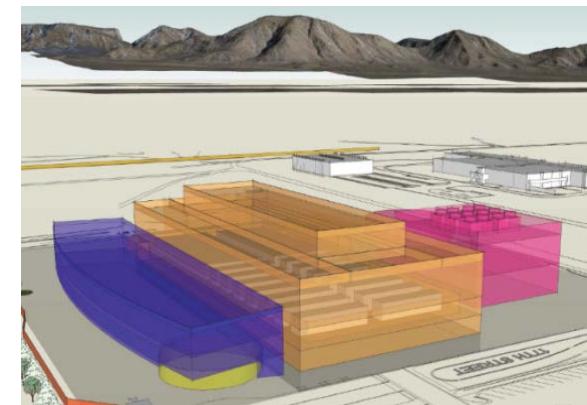
# Trusted & Strategic Rad-Hard Futures at Sandia



- Developing 180/150nm Technology
  - Based on BAE's technologies, but on SOI
  - Upgrading to process 200mm wafers
  - Strategic hardness with improved speed, density and configurability
- What is the proper Future capability?
  - Can CMOS be strategic rad-hard at 90nm?
    - 90nm sweet spot identified by customers for both analog and digital
    - Tradeoffs in cost, yield, and performance need addressed
  - CMOS fab, advanced packaging, design, and test/BI
  - 300mm advanced nodes for split-fab back-end-of-line?
  - Expanded R&D capabilities
  - Heterogeneous Integration



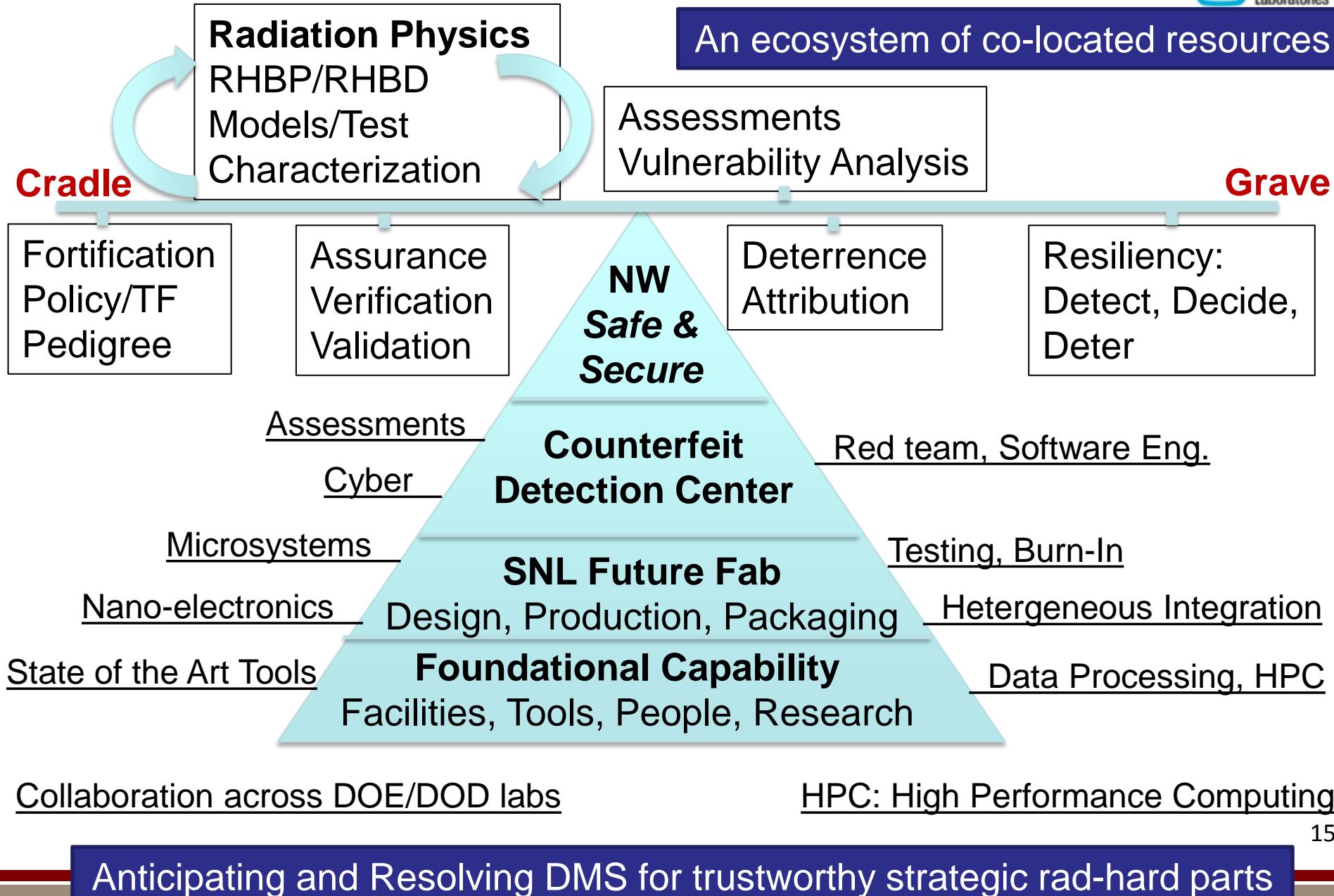
Stacking & Heterogeneous Integration



Next Generation Facility



MESA Complex



# Summary

- Rad-hard Trusted solutions exist today and will continue to be available in the near future
- Access to trustworthy rad-hard microelectronics will become more difficult due to DMS: consolidation, movement off-shore, closing of factories
- Measuring Trust and engineering Trust present difficult research problems with national-scale impact
- Sandia is addressing these complexities by developing the capabilities, tools, people, research programs, and facilities required to help secure trusted rad-hard microelectronics in the future